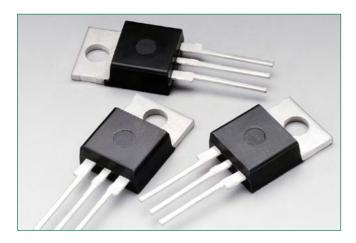
Surface Mount – 800V





### **Additional Information**







Accessories



Samples

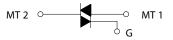
### **Description**

The BTB16 is designed for high performance full-wave AC control applications where high noise immunity and high commutating di/dt are required.

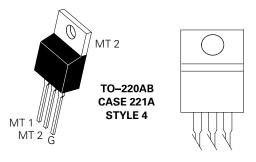
#### **Features**

- Blocking Voltage to 800 V
- On-State Current Rating of 16 Amperes RMS at 80°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt 1500 V/µs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dl/dt 7.5 A/ms minimum at 125°C
- These are Pb-Free Devices

### **Functional Diagram**



#### **Pin Out**





Surface Mount - 800V

## **Maximum Ratings** (T<sub>1</sub> = 25°C unless otherwise noted)

| Rating  |   | Symbol                                 | Value                   | Unit  |
|---|---|--|-------------------------|-------|
| Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J = -40^{\circ}$ to 125°C) | BTB16-600BW3G<br>BTB16-700BW3G<br>BTB16-800BW3G | V <sub>DRM</sub> ,<br>V <sub>RRM</sub> | 600<br>700<br>800       | V     |
| On-State RMS Current (Full Cycle Sine Wave, 60 Hz, $T_c = 8$  | 0°C)  | I <sub>T (RMS)</sub>                   | 16                      | А     |
| Peak Non-Repetitive Surge Current (One Full Cycle Sine Wa   | ve, 60 Hz, T <sub>c</sub> = 25°C)               | I <sub>TSM</sub>                       | 170                     | А     |
| Circuit Fusing Consideration (t = 8.3 ms)   |   | l²t                                    | 120                     | A²sec |
| Non-Repetitive Surge Peak Off-State Voltage ( $T_J = 25^{\circ}$ C, t = 8.3 ms)                             |   | $V_{DSM}/V_{RSM}$                      | $V_{DSM}/V_{RSM} + 100$ | V     |
| Peak Gate Current ( $T_J = 125$ °C, t $\leq 20\mu$ s)   |   | I <sub>GM</sub>                        | 4.0                     | W     |
| Average Gate Power (T <sub>J</sub> = 125°C)   |   | $P_{G(AV)}$                            | 1.0                     | W     |
| Operating Junction Temperature Range  |   | T <sub>J</sub>                         | -40 to +125             | °C    |
| Storage Temperature Range   |   | T <sub>stg</sub>                       | -40 to +150             | °C    |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the

### **Thermal Characteristics**

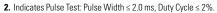
| Rating   |   | Symbol                               | Value     | Unit |
|--|---|--------------------------------------|-----------|------|
| Thermal Resistance                             | Junction-to-Case (AC) Junction-to-Ambient | R <sub>ejc</sub><br>R <sub>eja</sub> | 1.9<br>60 | °C/W |
| Maximum Lead Temperature for Soldering Purpose | s, 1/8" from case for 10 seconds          | T,                                   | 260       | °C   |

### Electrical Characteristics - OFF (T<sub>j</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

| Characteristic                         |                       | Symbol             | Min | Тур | Max   | Unit |
|--|-----------------------|--------------------|-----|-----|-------|------|
| Peak Repetitive Blocking Current       | T <sub>1</sub> = 25°C | I <sub>DRM</sub> , | -   | -   | 0.005 | A    |
| $(V_D = V_{DRM} = V_{RRM}; Gate Open)$ | T = 125°C             | I                  | -   | -   | 2.0   | mA   |

## Electrical Characteristics - ON (T<sub>1</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

| Characteristic  |              | Symbol          | Min | Тур | Max  | Unit |
|---|--------------|-----------------|-----|-----|------|------|
| Forward On-State Voltage (Note 2) ( $I_{TM} = \pm 17 \text{ A Peak}$ )                          |              | $V_{TM}$        | -   | -   | 1.55 | V    |
|   | MT2(+), G(+) |                 | 2.5 | _   | 50   |      |
| Gate Trigger Current (Continuous dc) $(V_D = 12 \text{ V}, R_L = 30 \Omega)$                    | MT2(+), G(-) | I <sub>GT</sub> | 2.5 | _   | 50   | mA   |
|   | MT2(-), G(-) |                 | 2.5 | _   | 50   |      |
| Holding Current ( $V_D = 12 \text{ V}$ , Gate Open, Initiating Current = $\pm 150 \text{ mA}$ ) |              | I <sub>H</sub>  | _   | _   | 60   | mA   |
|   | MT2(+), G(+) |                 | _   | _   | 70   |      |
| Latching Current ( $V_D = 12 \text{ V}, I_G = 50 \text{ mA}$ )                                  | MT2(+), G(-) | I               | _   | _   | 90   | mA   |
|   | MT2(-), G(-) |                 | _   | _   | 70   |      |
|   | MT2(+), G(+) |                 | 0.5 | _   | 1.7  |      |
| Gate Trigger Voltage ( $V_D = 12 \text{ V}, R_I = 30 \Omega$ )                                  | MT2(+), G(-) | V <sub>GT</sub> | 0.5 | -   | 1.1  | V    |
|   | MT2(-), G(-) | -               | 0.5 | _   | 1.1  |      |
|   | MT2(+), G(+) |                 | 0.2 | -   | -    |      |
| Gate Non-Trigger Voltage ( $T_J = 125$ °C)  | MT2(+), G(-) | $V_{gd}$        | 0.2 | _   | _    | V    |
|   | MT2(-), G(-) | 35              | 0.2 | _   | _    |      |





Recommended Operating Conditions may affect device reliability.

1. V<sub>DBM</sub> and V<sub>BBM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Surface Mount – 800V

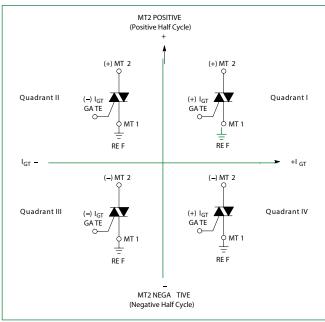
## **Dynamic Characteristics**

| Characteristic  | Symbol   | Min  | Тур | Max | Unit |
|---|----------|------|-----|-----|------|
| Rate of Change of Commutating Current, See Figure 10. (Gate Open, $T_J = 125^{\circ}$ C, No Snubber)                                | (dl/dt)c | 7.5  | -   | -   | A/ms |
| Critical Rate of Rise of On–State Current ( $T_J = 125^{\circ}\text{C}$ , $f = 120$ Hz, $I_G = 2 \times I_{GT}$ , tr $\leq 100$ ns) | dl/dt    | _    | _   | 50  | A/µs |
| Critical Rate of Rise of Off-State Voltage $(V_D = 0.66 \times V_{DRM}, Exponential Waveform, Gate Open, T_J = 125°C)$              | dV/dt    | 1500 | _   | _   | V/µs |

### **Voltage Current Characteristic of SCR**

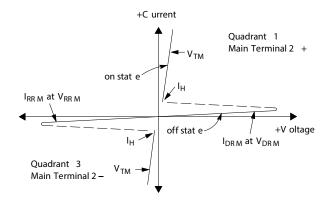
| Symbol           | Parameter                                 |
|------------------|---|
| $V_{DRM}$        | Peak Repetitive Forward Off State Voltage |
| I <sub>DRM</sub> | Peak Forward Blocking Current             |
| $V_{RRM}$        | Peak Repetitive Reverse Off State Voltage |
| I <sub>RRM</sub> | Peak Reverse Blocking Current             |
| $V_{TM}$         | Maximum On State Voltage                  |
| I <sub>H</sub>   | Holding Current                           |

#### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in—phase signals (using standard AC lines) quadrants I and III are used



Surface Mount – 800V

**Figure 1. Typical RMS Current Derating** 

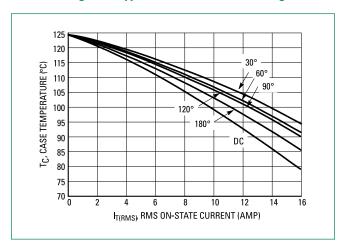
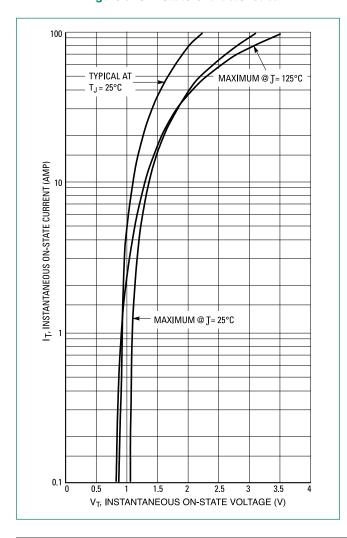
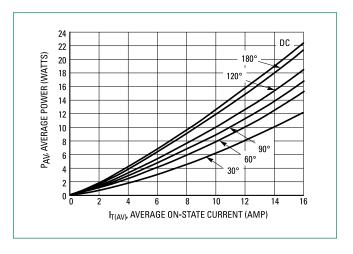


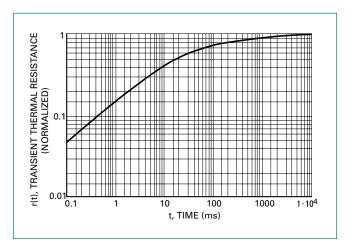
Figure 3. On-State Characteristics



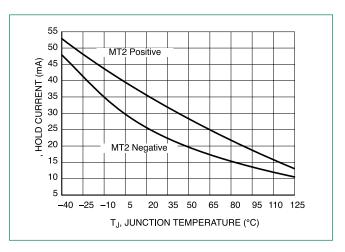
**Figure 2. On-State Power Dissipation** 



**Figure 4. Thermal Response** 



**Figure 5. Typical Hold Current Variation** 





Surface Mount – 800V

**Figure 6. Typical Gate Trigger Current Variation** 

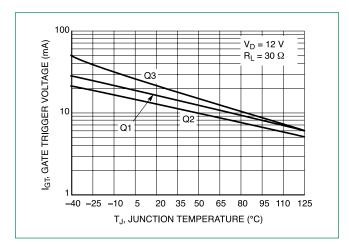


Figure 7. Typical Gate Trigger Voltage Variation

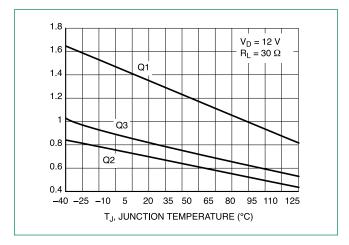
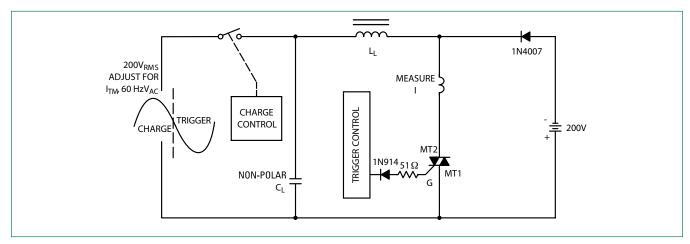


Figure 8. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)

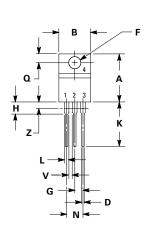


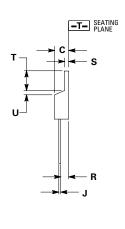
Note: Component values are for verification of rated (di/dt)c. See AN1048 for additional information



Surface Mount – 800V

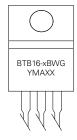
### **Dimensions**





### **Part Marking System**





Y =Year M =Month A =Assembly Site

XX =Lot Serial Code G =Pb-Free Package

| <b>5</b> . | Inches |       | Millim | neters |
|------------|--------|-------|--------|--------|
| Dim        | Min    | Max   | Min    | Max    |
| Α          | 0.590  | 0.620 | 14.99  | 15.75  |
| В          | 0.380  | 0.420 | 9.65   | 10.67  |
| С          | 0.178  | 0.188 | 4.52   | 4.78   |
| D          | 0.025  | 0.035 | 0.64   | 0.89   |
| F          | 0.142  | 0.147 | 3.61   | 3.73   |
| G          | 0.095  | 0.105 | 2.41   | 2.67   |
| Н          | 0.110  | 0.130 | 2.79   | 3.30   |
| J          | 0.018  | 0.024 | 0.46   | 0.61   |
| K          | 0.540  | 0.575 | 13.72  | 14.61  |
| L          | 0.060  | 0.075 | 1.52   | 1.91   |
| N          | 0.195  | 0.205 | 4.95   | 5.21   |
| Q          | 0.105  | 0.115 | 2.67   | 2.92   |
| R          | 0.085  | 0.095 | 2.16   | 2.41   |
| S          | 0.045  | 0.060 | 1.14   | 1.52   |
| T          | 0.235  | 0.255 | 5.97   | 6.47   |
| U          | 0.000  | 0.050 | 0.00   | 1.27   |
| V          | 0.045  | -     | 1.15   | -      |
| Z          | -      | 0.080 | -      | 2.04   |

| Pin Assignment |                 |  |  |
|----------------|-----------------|--|--|
| 1              | Main Terminal 1 |  |  |
| 2              | Main Terminal 2 |  |  |
| 3              | Gate            |  |  |
| 4              | Main Terminal 2 |  |  |

### **Ordering Information**

| Device        | Package               | Shipping         |
|---------------|-----------------------|------------------|
| BTB16-600BW3G | TO-220AB<br>(Pb-Free) | 1000 Units / Box |
| BTB16-700BW3G | TO-220AB<br>(Pb-Free) | 1000 Units / Box |
| BTB16-800BW3G | TO-220AB<br>(Pb-Free) | 1000 Units / Box |



<sup>1.</sup> Dimensioning and tolerancing per ansi y14.5m, 1982.

Controlling dimension: inch.
 Dimension z defines a zone where all body and lead irregularities are allowed.